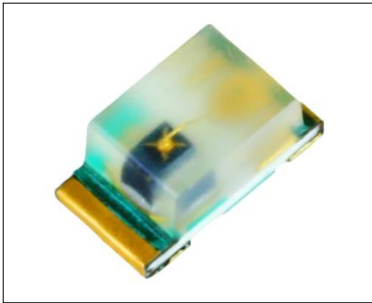


Standard product specifications

VFHL1111C-4B23C-TR



Features

Package	1608 Flat lens type, Milky white resin, Green color emitting LED Outer dimension 1.6 x 0.8 x 0.7mm (L x W x H)
Product features	<ul style="list-style-type: none"> •Equivalent to JEDEC level 3 (IPC/JEDEC J-STD-020D) •Lead-free soldering compatible •RoHS compliant

Recommended applications

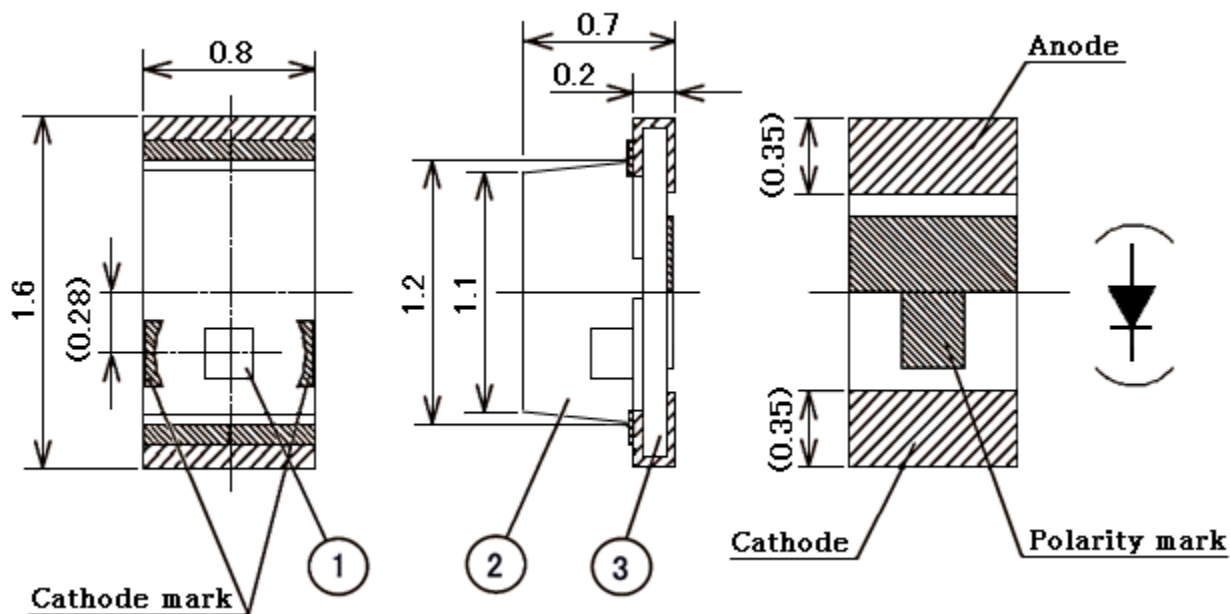
- Indicators for automotive, consumer equipment etc.

Outline dimensions

VFHL1111C-4B23C-TR

Unit
Weight
Tolerance

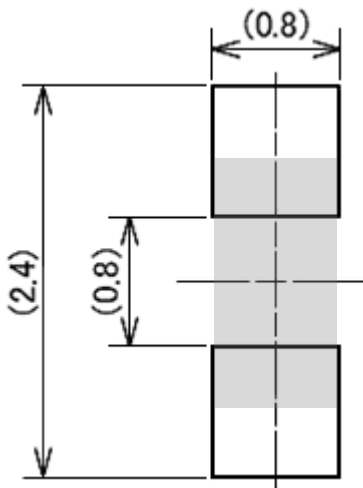
: mm
: 1.4mg
: ±0.1



No.	Part name	Material	Qty.
①	LED die	AlGaInP	1
②	Mold resin	Epoxy resin	1
③	Substrate	Glass fabrics	1

Recommended pad

Unit : mm



Specifications

VFHL1111C-4B23C-TR

【 Product overview 】

Die material	AlGaInP
Emitting color	Green
Resin color	Milky white

【 Absolute maximum ratings 】

(Ta=25°C)

Item	Symbol	Maximum ratings	Units
Power dissipation	P _d	78	mW
Forward current	I _F	30	mA
Repetitive peak forward current "1ms, 1/20 duty"	I _{FRM}	100	mA
I _F derate linearly from "75°C"	ΔI _F	1.00	mA/°C
I _{FRM} derate linearly from "75°C"	ΔI _{FRM}	3.33	mA/°C
Reverse voltage	V _R	5	V
Operating temperature	T _{opr}	-40 to +100	°C
Storage temperature	T _{stg}	-40 to +105	°C
Electro Static Discharge threshold "HBM"	ESD	1,000	V
Soldering temperature "reflow soldering"	T _{sld}	260	°C

Notes 1

Notes 2

Notes 1 ESD testing method : EIAJ4701/300(304) Human body model (HBM) 1.5kΩ,100pF

Notes 2 Please refer to page 8, "Soldering Conditions".

【 Thermal characteristics 】

(Ta=25°C)

Item	Symbol	Typ.	Max.	Units
Thermal resistance 【Junction - Ambient】	R _{th(j-a)}	550	-	°C/W
Thermal resistance 【Junction - Solder point】	R _{th(j-s)}	330	-	°C/W
Junction Temperature	T _j	-	105	°C

Notes 3

Notes 3 R_{th(j-a)} Measurement Condition

• Substrate : FR4(t=1.6mm)

• Pattern Size : 16mm²

Specifications

VFHL1111C-4B23C-TR

【 Electro and optical characteristics 】

(Ta=25°C)

Item	Symbol	Conditions	Min.	Typ.	Max.	Units
Forward voltage	V _F	I _F = 20mA	-	1.9	2.4	V
Reverse current	I _R	V _R = 5V	-	-	10	μA
Luminous intensity	I _V	I _F = 20mA	12	18	27	mcd
Luminous flux	φ _V	I _F = 20mA	-	55	-	mlm
Peak wavelength	λ _p	I _F = 20mA	-	565	-	nm
Dominant wavelength	λ _d	I _F = 20mA	558	562	567	nm
Spectral line half width	Δλ	I _F = 20mA	-	15	-	nm
Half intensity angle	2θ1/2	I _F = 20mA	-	140	-	deg.

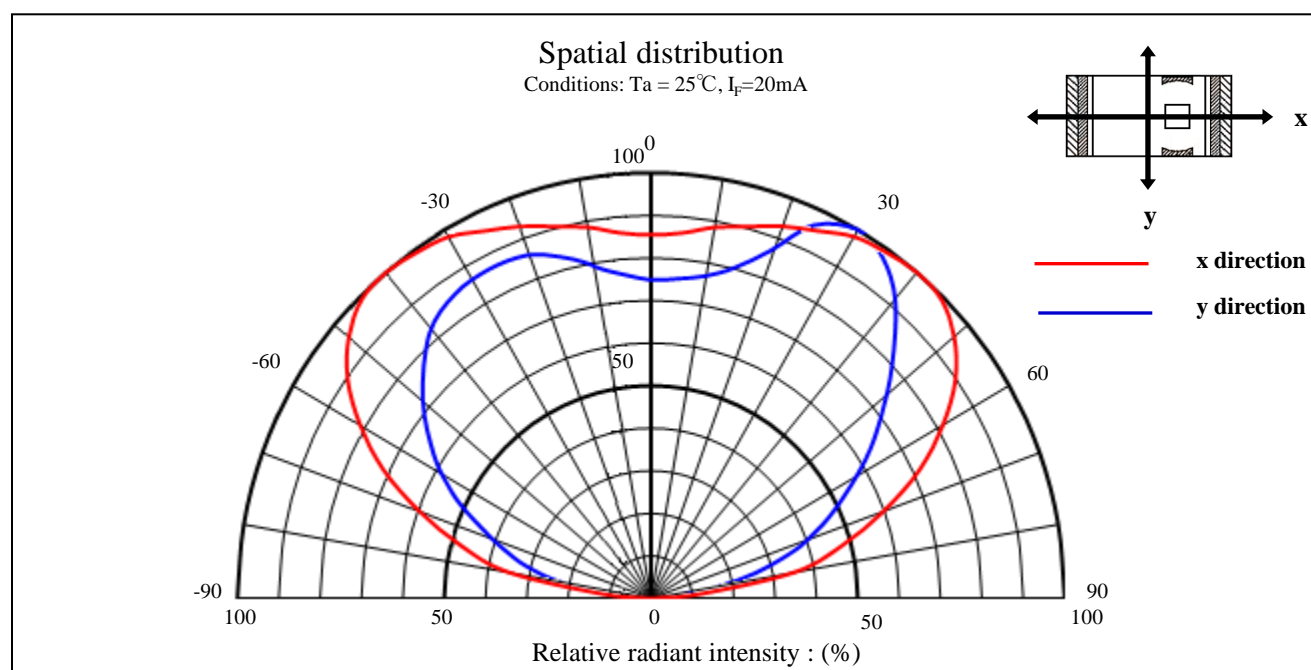
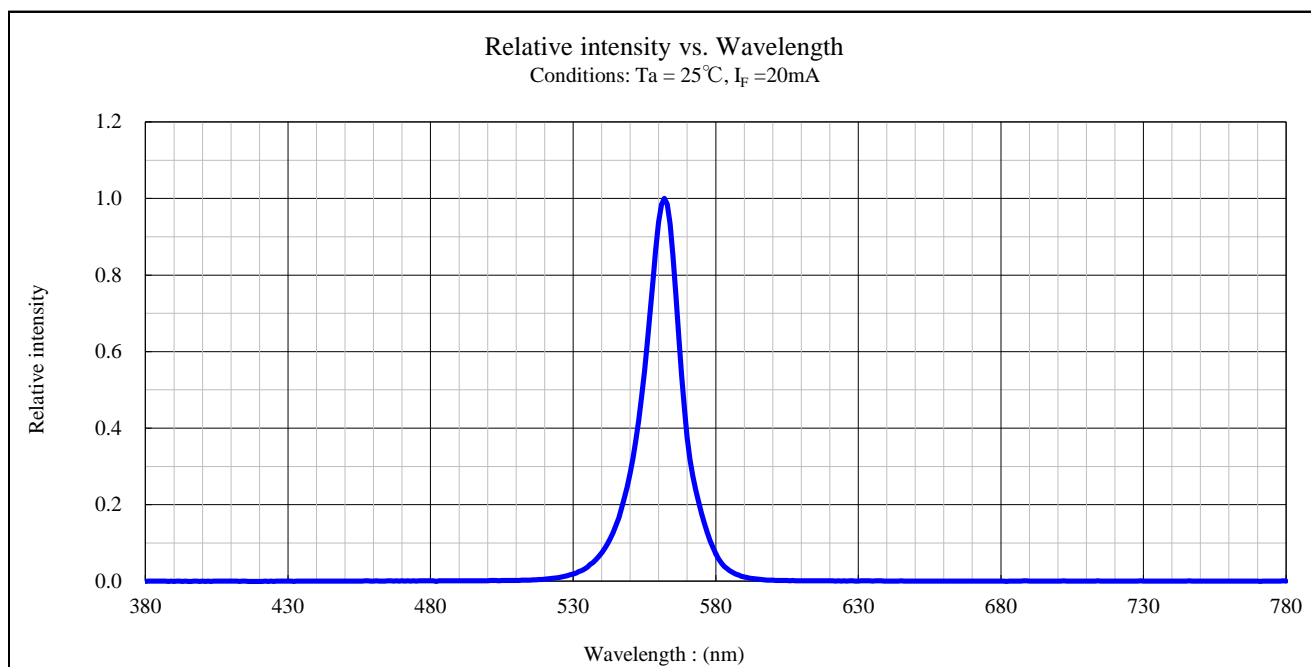
Notes Above the table of luminous intensity (I_V) values and dominant wavelength (λ_d) values are the setup value of the selection machine. 【Tolerance : I_V...±10%, λ_d...±1nm】

【 Sorting for luminous intensity and dominant wavelength 】

LEDs shall be sorted out into the following ranks of luminous intensity and dominant wavelength.

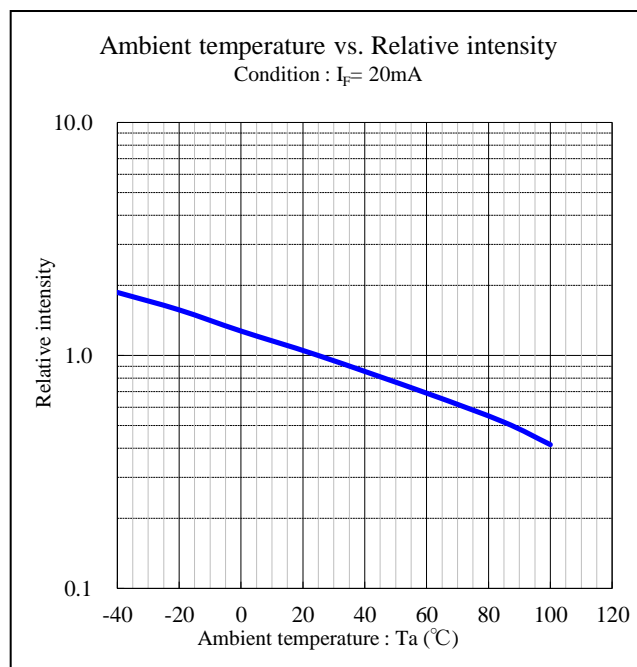
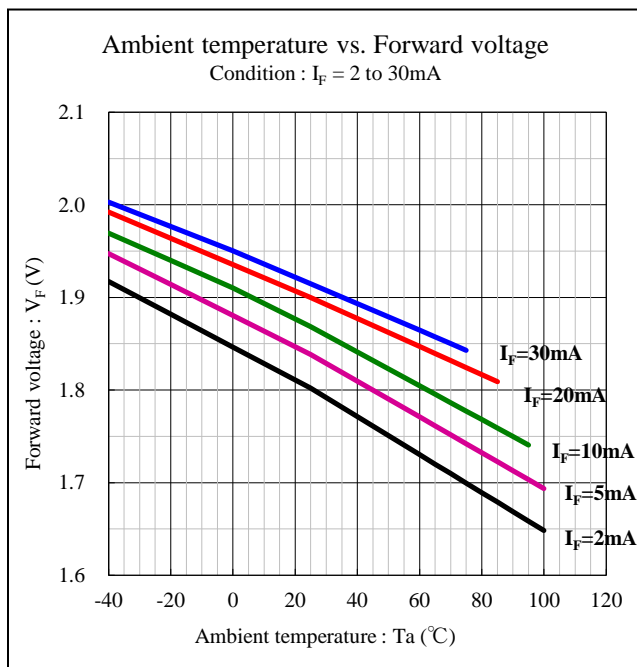
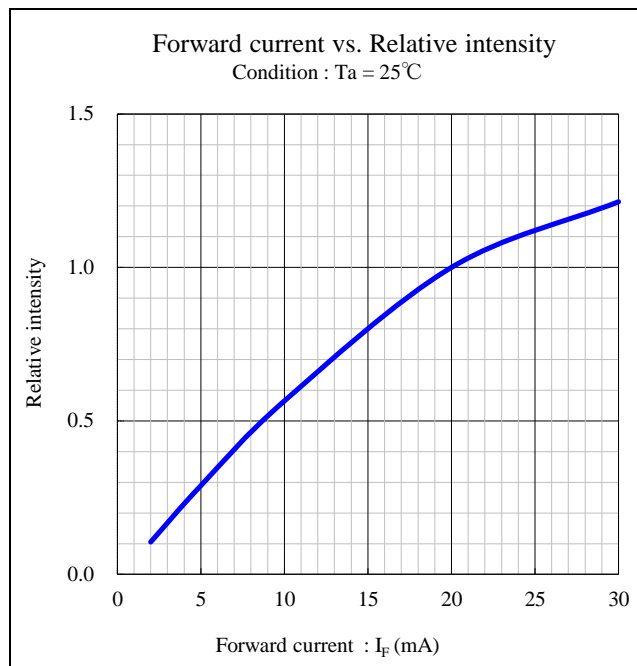
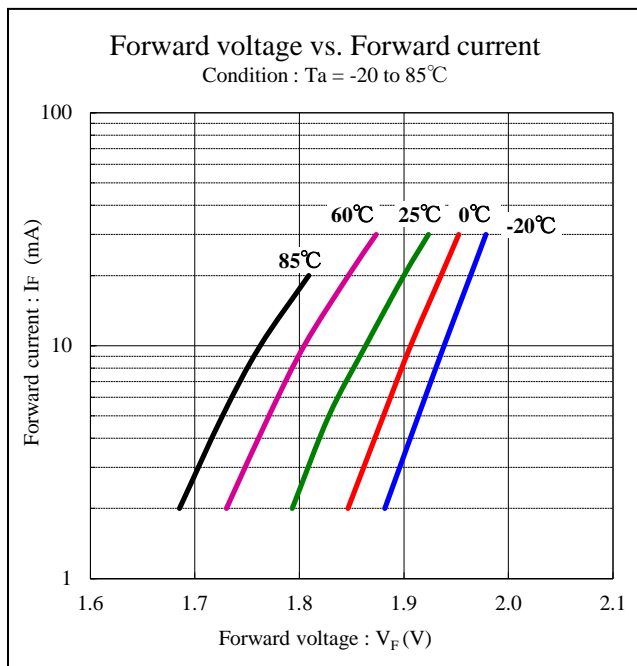
Luminous intensity (I _V) rank				Dominant wavelength (λ _d) rank			
Rank	I _V (mcd)		Conditions	Rank	λ _d (nm)		Conditions
	Min.	Max.			Min.	Max.	
B2	12	15	I _F =20mA Ta=25°C	C	558	561	I _F =20mA Ta=25°C
B3	15	18		D	561	564	
B4	18	22		E	564	567	
B5	22	27					

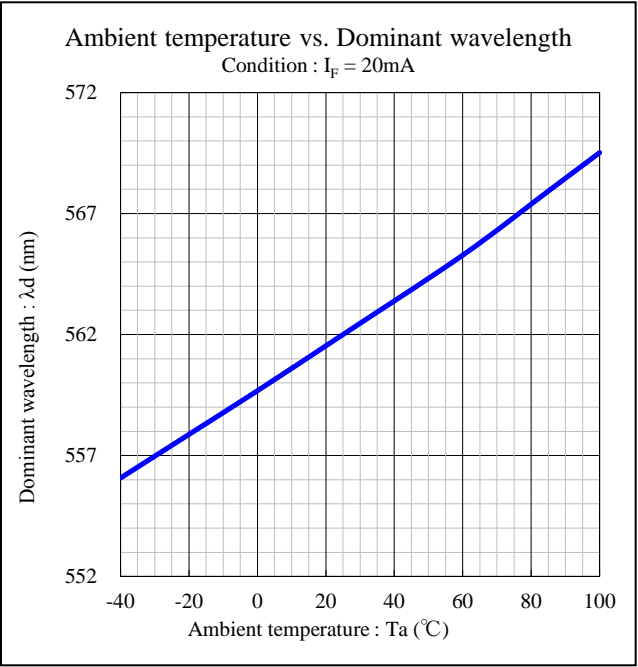
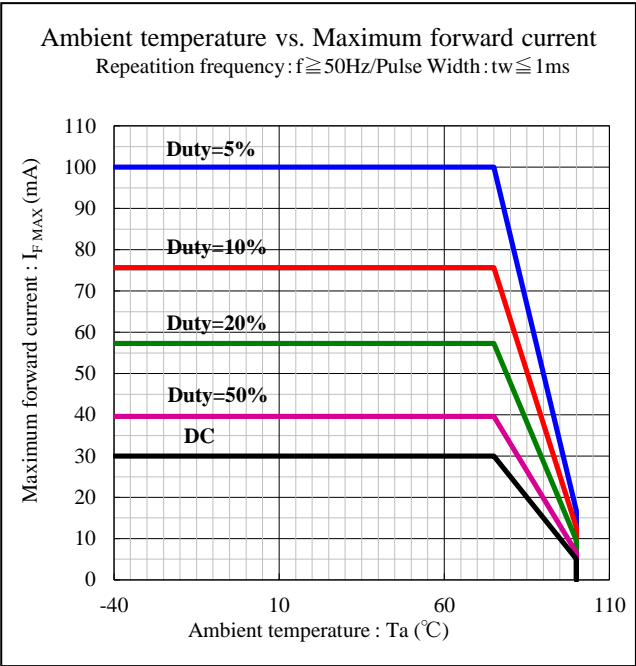
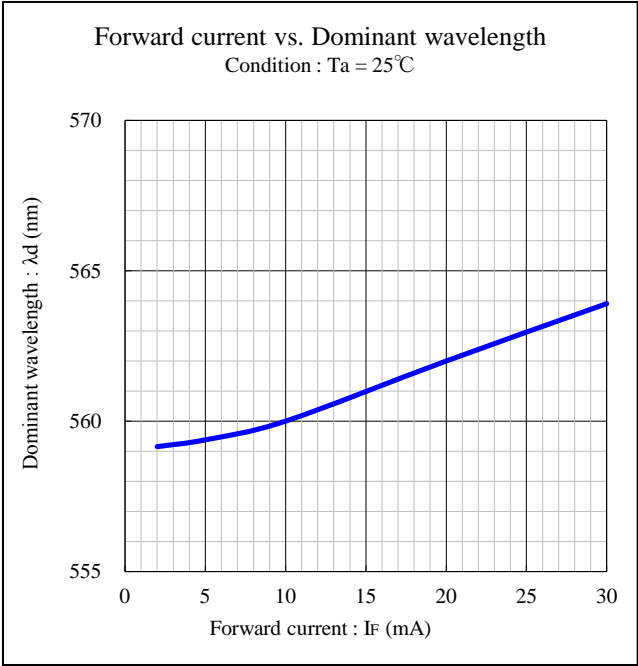
Notes Above the table of luminous intensity (I_V) values and dominant wavelength (λ_d) values are the setup value of the selection machine. 【Tolerance : I_V...±10%, λ_d...±1nm】



Technical data

VFHL1111C-4B23C-TR



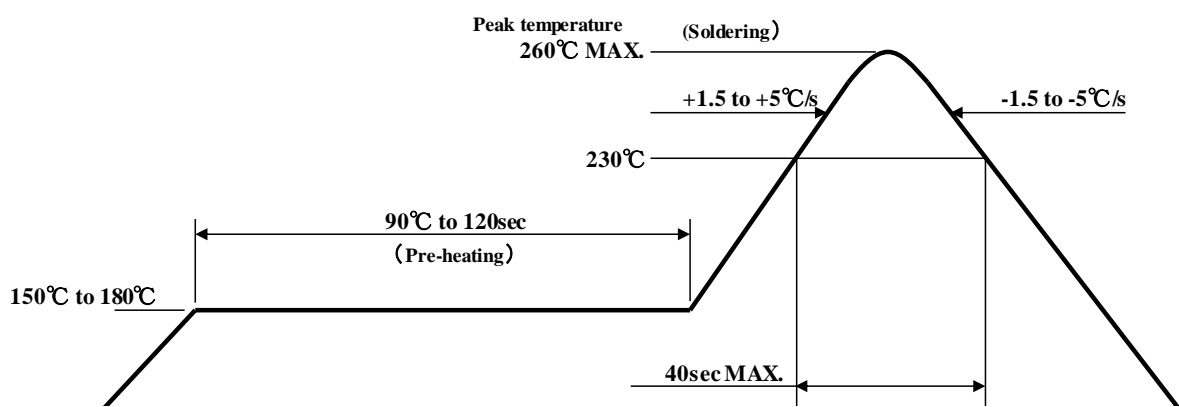


【Soldering precaution】

(acc.to EIAJ-4701/300)

1. Heat stress during soldering will influence the reliability of LEDs, however that effect will vary on heating method. Also, if components of varying shape are soldered together, it is recommended to set the soldering pad temperature according to the component most vulnerable to heat (e.g., surface mount LED).
2. LED parts including the resin are not stable immediately after soldering (when they are not at room temperature), any mechanical stress may cause damage to the product. Please avoid such stress after soldering, especially stacking of the boards which may cause the boards to warp and any other types of friction with hard materials.
3. High hardness silicone resin is used for this product's lens, but the silicone resin has the characteristic that softens at the high temperature. There is a possibility of causing the transformation, the breakage, and peeling off of the lens when it touches the resin lens at the high temperature such as immediately after soldering. Please avoid touching the lens at the high temperature.
4. Recommended temperature profile for the Reflow soldering is listed as the temperature of the resin surface. Temperature distribution varies on heating method, PCB material, other components in the assembly, and mounting density .
Please do not repeat the heating process in Reflow process more than twice.

【Recommended reflow soldering condition】



- Notes 1 Temperature Profile for the reflow should be set to the surface temperature of resin which is on the top of LED. This should be the maximum temperature for soldering. Lowering the heating temperature and decreasing heating time is very effective in achieving higher reliability.
- Notes 2 The reflow soldering process should be done up to twice(2 times Max). When second process is performed, interval between first and second process should be as short as possible to prevent absorption of moisture to resin of LED. The second soldering process should not be done until LEDs have returned to room temperature (by nature-cooling) after first soldering process.

- If soldering manually, Stanley recommends using a soldering iron equipped with temperature control. During the actual soldering process, make sure that the soldering iron never touches the LED itself, and avoid the LED's electrode heating temperature reaching above the heating temperature of the solder pad. All repairs must be performed only once in the same spot, and please avoid reusing components.
- In soldering process, immediately after iron tip is cleaned, please make sure that the soldering iron reaches the appropriate temperature, before using. Also, please avoid applying any types of pressure to the soldered components before the solder has been cooled and hardened, as it may deteriorate solder performance and solder quality.

【Recommended manual soldering condition】

Temperature of iron tip	350℃ max.
Soldering duration, time	3sec. max., 1 time

- When using adhesive material for tentative fixatives, thermosetting resin or Ultraviolet radiation (UV) setting resin with heat shall be recommended.
- When cleaning, isopropyl alcohol shall be recommended. Some chemicals, including Freon substitute detergent could corrode or affect the optical characteristics of the lens or the casing surface. Please review the reference chart below for cleaning.
Cleaning with ultrasonic shall not be recommended.
- Flow soldering (dip soldering) is not recommended for this product.

Cleaning agents	Recommended / Not recommended
Isopropyl alcohol	✓ Recommended
Trichloroethylene	x Not recommended
Chlorothene	x Not recommended
Acetone	x Not recommended
Thinner	x Not recommended

【Other precautions】

1. Stanley LED Lamps have semiconductor characteristics and are designed to ensure high reliability. However, the performance may vary depending on usage conditions.
2. Absolute maximum ratings are set to prevent LED lamps from failing due to excess stress(temperature, current, voltage, etc.). Usage conditions must not exceed the ratings for a moment, nor do reach one item of absolute maximum ratings simultaneously.
3. In order to ensure high reliability from LED Lamps, variable factors that arise in actual usage conditions should be taken it to account for designing. (derating of typ., max. forward voltage, etc.)
4. Please insert straight protective resistors into the circuit in order to stabilize LED operation and to prevent the device from igniting due to excess current.
5. Please be careful when LED is soldered on a metal plate, since solder crack might be caused by heat .
6. Please avoid using this product with materials or products that contain sulfur or chlorine element which may damage the product. Keep the product in desiccator regardless of before or after mounting to prevent corrosive gas. Also make sure there is no corrosive gas which occurs in surrounding area or invade from outside when using products.
7. Please avoid the stick of foreign material because molding resin in the products have adhesiveness. And please don't touch lens portion.
8. Please check the actual performance in the assembly because the specification sheets are described for LED device only.
9. Please refrain from looking directly at the light source of LED at high output, as it may harm your vision.
10. The products are designed to operate without failure in recommended usage conditions. However, please take the necessary precautions to prevent fire, injury, and other damages should any malfunction or failure arise.
11. The products are manufactured to be used for ordinary electronic equipment. Please contact our sales staff beforehand when exceptional quality and reliability are required, and the failure or malfunction of the products might directly jeopardize life or health (such as for airplanes, aerospace, transport equipment, medical applications, nuclear reactor control systems and so on).
12. The formal specification sheets shall be valid only by exchange of documents signed by both parties.

This products are baked (moisture removal) before packaging, and are shipped in moisture-proof packaging (as shown below) to minimize moisture absorption during transportation.

However, in regards to storing the products, the use of dry-box under the following conditions is recommended. Moisture-proof bag as the packaging is made of anti-static material but packaging box is not.

【Recommended storage condition / products warranty period】

Temperature	+5 to 30°C
Humidity	Under 70%

In the case of the package unopened , **6 months under 【 Recommended storage condition 】**. Please avoid rapid transition from low temp. condition to high temp. condition and storage in corroding and dusty environment.

【Time elapsed after package opening】

The package should not be opened until immediately prior to its use, and please keep the time frame between package opening and soldering which is **【maximum 168h】**.

If the device needs to be soldered twice, both soldering operations must be completed within 168h.

If any components should remain unused, please reseal the package and store them under the conditions described in the **【 Recommended storage condition 】** above.

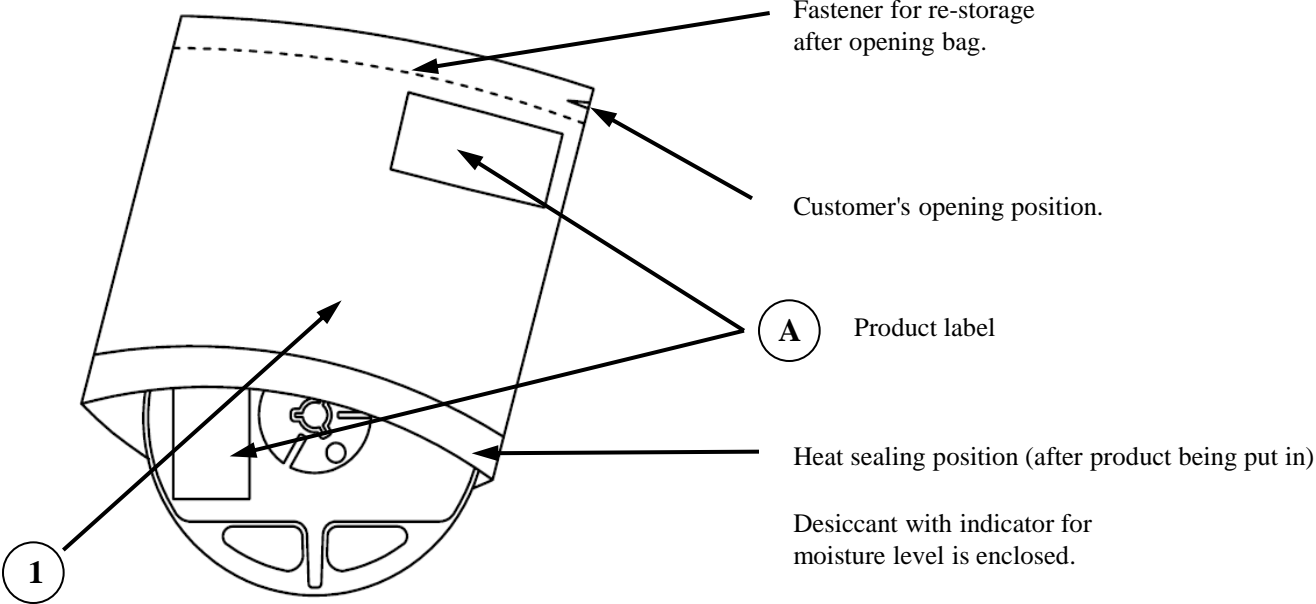
This product must be required to perform baking process (moisture removal) for **10h(min.) to 12h(max.) at 60+/-5 degrees Celsius** if following conditions apply.

1. In the case of silica gel (blue) which indicates the moisture level within the package, changes or loses its blue color.
2. In the case of time passes for 168h after the package is opened once.

Baking process should be performed after LED having been taken out of the package.

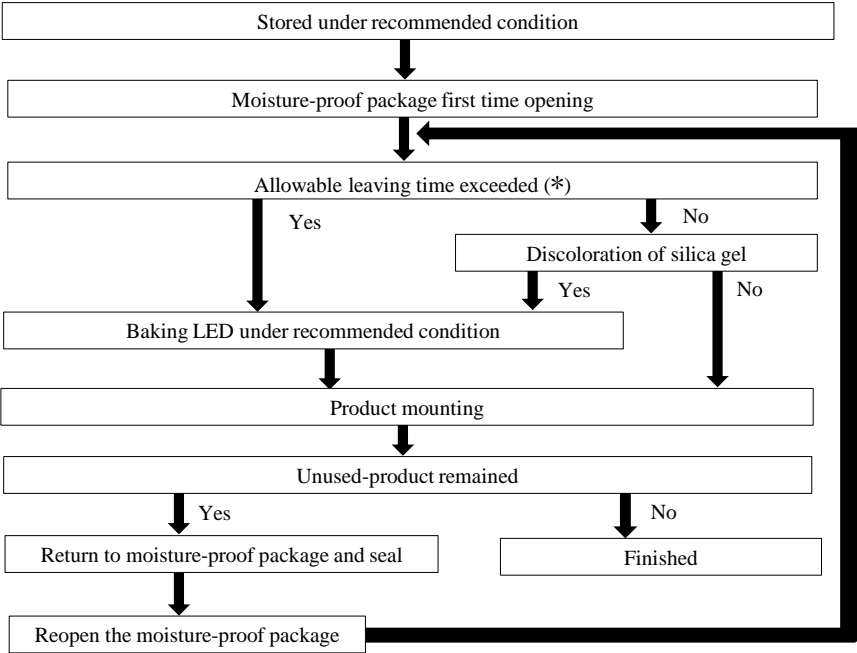
Baking may be performed in the tape-reel form , however if it is performed with the reel stacked over one another, it may cause deformation of the reels and taping materials and later obstruct mounting. Please handle only once it has returned to room temperature. Provided that, baking process shall be 2 times max.

【Moisture-proof packaging specification】



NO.	Part name	Material	Remarks
①	Moisture-proof bag with Aluminum layer	PET+Al+PE	with ESD protection

【Flow chart-package opening to mounting】



Allowable leaving time means the maximum allowable leaving time after opening package, which depends on each LED type.

The allowable leaving time should be calculated form the first opening of package to the time when soldering process is finished.

When judging if the allowable leaving time has exceeded or not, please subtract the soldering time. The allowable leaving time after reopening should be calculated form the first opening of package, or from the time when baking process is finished.

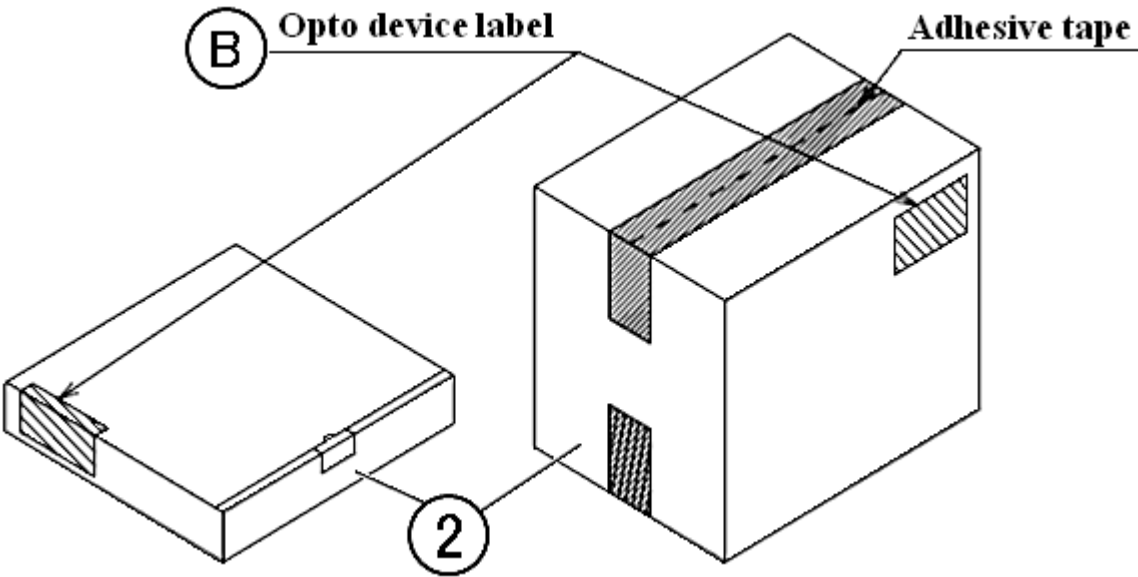
【Packing box】

(RoHS2 / ELV Compliant)

Box type	Outline dimension L x W x H (mm)	Capacity of the box
Type A	280 x 265 x 45	3 reels
Type B	310 x 235 x 265	15 reels
Type C	440 x 310 x 265	30 reels

The above measure is all the reference value.

The box is selected out of the above table by shipping quantity.



Type A

Material / box : Cardboard C5BF

Type B,C

Material / box : Cardboard K5AF

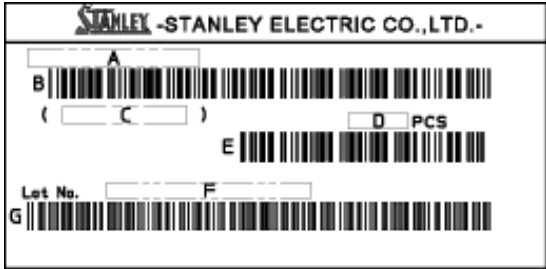
Partition : Cardboard K5AF

No.	Part name	Material	Remarks
②	Packing box	Corrugated cardbord	without ESD protection

【Label specification】

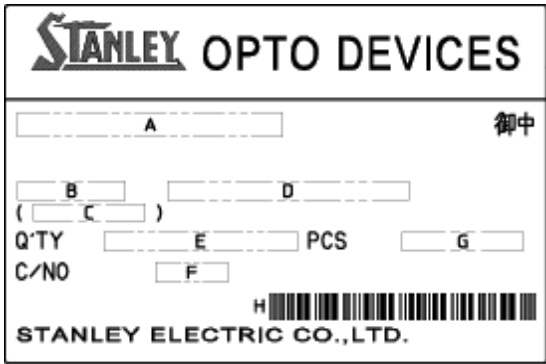
(acc.to JIS-X0503(Code-39))

A Product label



- A. Parts number
 - B. Bar-code for parts number
 - C. Parts code (In-house identification code for each parts number)
 - D. Packed parts quantity
 - E. Bar-code for packed parts quantity
 - F. Lot number & rank
- (refer to lot number notational system for details)
- G. Bar-code for lot number & rank

B Opto device label



- A. Customer name
- B. Parts type
- C. Parts code
- D. Parts number
- E. Packed parts quantity
- F. Carton number
- G. Shipping date
- H. Bar-code for In-house identification number

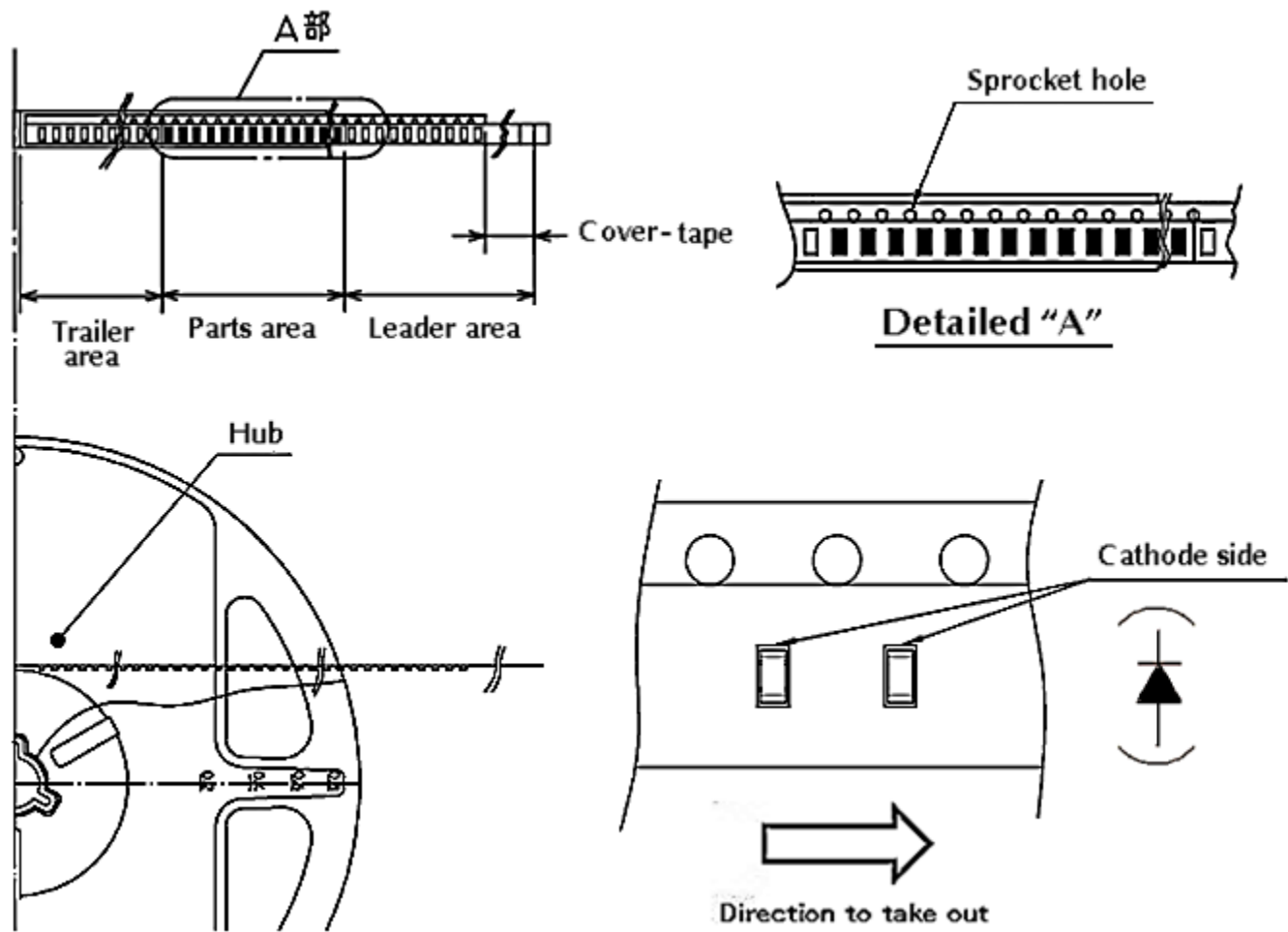
<Remarks> Bar-code font : acc.to Code-39(JIS-X0503)

Taping and reel specifications

VFHL1111C-4B23C-TR

(acc.to JIS-C0806-03)

【Appearance】



Note
"-TR" means cathode Side of LEDs should be placed on the sprocket-hole side.

Items		Specifications	Remarks
Leader area	Cover-tape	Cover-tape shall be longer than 200mm without carrier-tape	The end of cover-tape shall be held with adhesive tape.
	Carrier-tape	Empty pocket shall be more than 10 pieces.	Please refer to the above figure for Taping & reel orientation .
Trailer area		Empty pocket shall be more than 15 pieces.	The end of taping shall be inserted into a slit of the hub.

Taping and reel specifications

VFHL1111C-4B23C-TR

(acc.to JIS-C0806-03)

【Qty. per reel】

4,000parts/reel

Minimum Qty. per reel might be 500 parts when getting less than 4,000 parts.

In such case, parts of 500-unit-qty. shall be packed in a reel and the qty.shall be identified on the label

【Mechanical strength】

Cover-tape adhesive strength shall be 0.1～1.0N (An angle between carrier-tape and cover-tape shall be170 deg.).

Both tapes shall be so sealed that the contained parts will not come out from the tape when it is bent at a radius of 15mm.

【Others】

Reversed-orientation, Up-side down placing, side placing and out of spec. parts mix shall not be held.

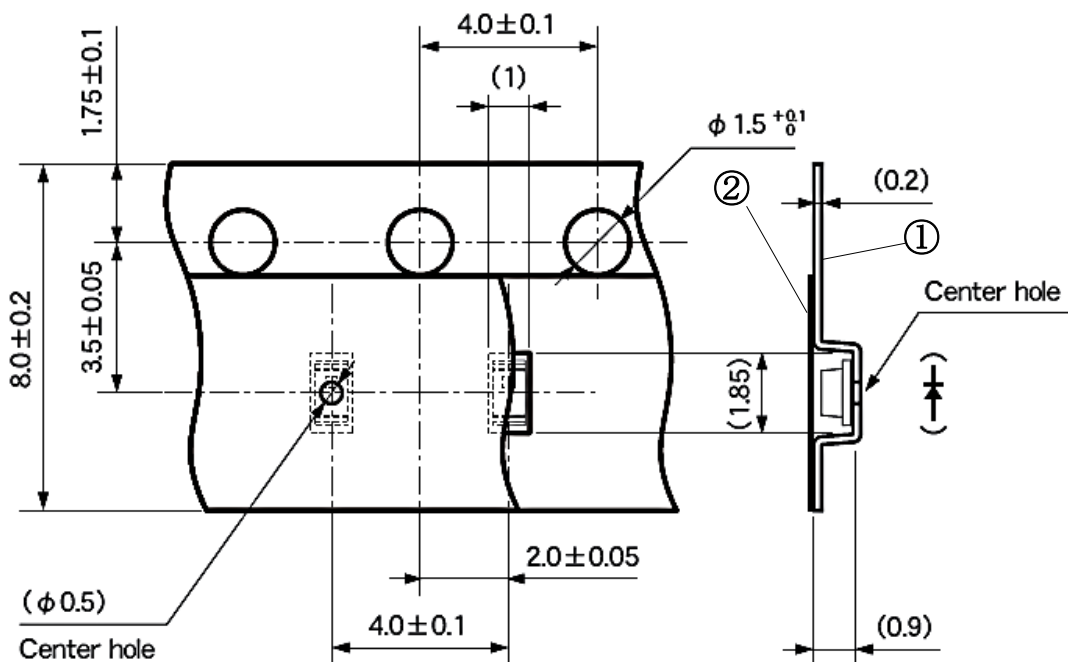
Max qty. of empty pocket per reel shall be defined as the following.

Qty./reel	Max. qty. of empty pocket	Remarks
500	1	-
1,000	1	-
1,500	2	-
2,000	2	No continuance
2,500	3	No continuance
3,000	3	No continuance
3,500	4	No continuance
4,000	4	No continuance

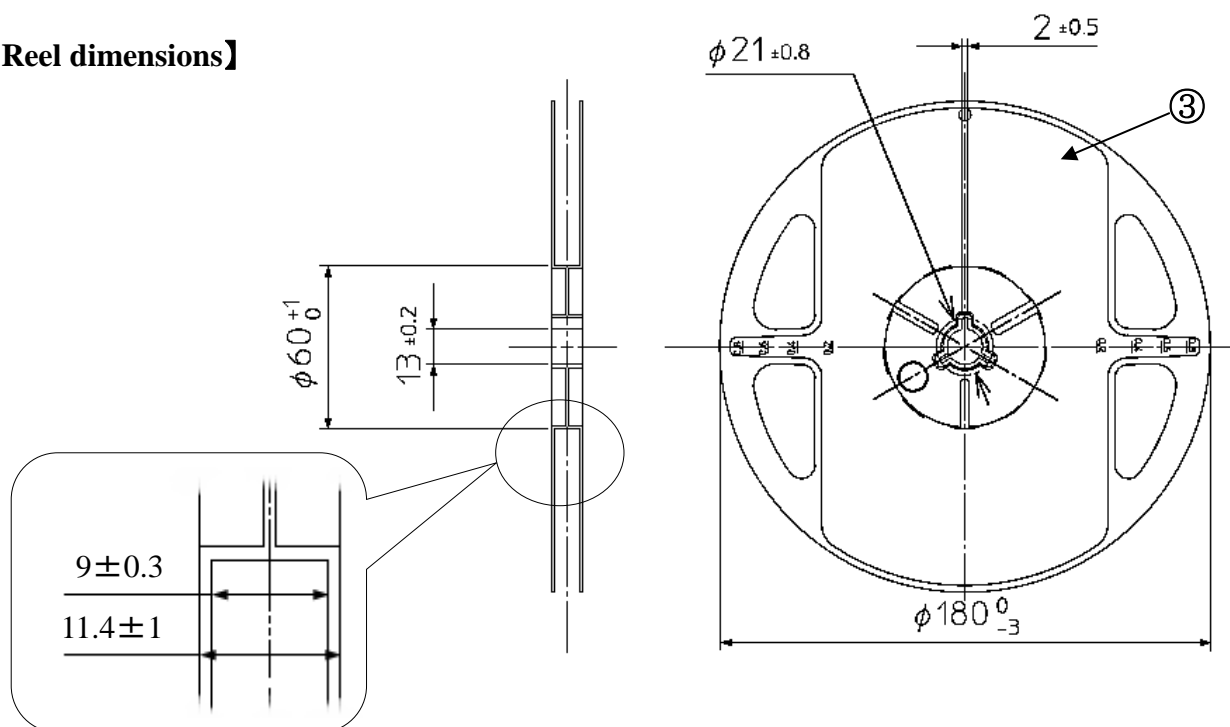
(acc.to JIS-C0806-03)

Unit: mm

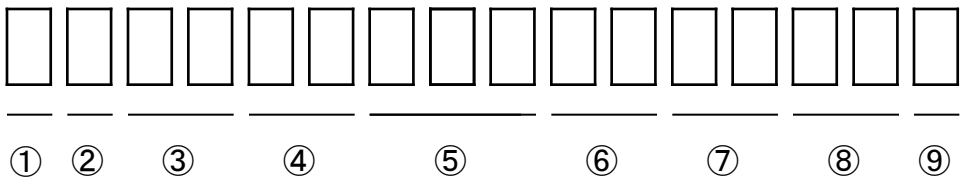
【Taping dimensions】



【Reel dimensions】



NO.	Part name	Remarks
①	Carrier reel	with ESD protection
②	Cover tape	with ESD protection
③	Carrier tape	with ESD protection



- ① - 1digit : Production location (mark identify alphabet)
- ② - 1digit : Production year (the last digit of production year 2020→0, 2021→1, 2022→2, 2023→3 …)
- ③ - 2digits : Production month (Jan. to Sep. ,should be 01,02,03 …)
- ④ - 2digits : Production date
- ⑤ - 3digits : Serial number
- ⑥ - 2digits : Tape and reel following number
- ⑦ - 2digits : Radiant intensity rank.
 (If radiant intensity rank is 1 digit, "-" shall be dashed on the place for the second digit.
 If there is no identified intensity rank, "- -" is used to indicate.)
- ⑧ - 2digits : Color / chromaticity rank
 (If color / chromaticity rank is 1 digit, "-" shall be dashed on the place for the second digit.
 If there is no identified intensity rank, "- -" is used to indicate.)
- ⑨ - 1digit : Option rank (Stanley normally print "-" to indicate)

This product is in compliance with RoHS2 / ELV.

Prohibition substance and it's criteria value of RoHS2 / ELV are as follows.

- RoHS2 instruction ... Refer to following 1 to 10.
- ELV instruction ... Refer to following 1 to 4.

No.	Substances	Thlreshold
1	Lead and its compounds	0.1% (1,000ppm)
2	Mercury and its compounds	0.1% (1,000ppm)
3	Cadmium and its compounds	0.01% (100ppm)
4	Hexavalent chromium compounds	0.1% (1,000ppm)
5	PBB : Polybrominated Biphenyls	0.1% (1,000ppm)
6	PBDE : Polybrominated Biphenyl Ethers	0.1% (1,000ppm)
7	DEHP : Bis (2-ethylhexyl) phthalate	0.1% (1,000ppm)
8	BBP : Butyl benzyl phthalate	0.1% (1,000ppm)
9	DBP : Dibutyl phthalate	0.1% (1,000ppm)
10	DIBP : Diisobutyl phthalate	0.1% (1,000ppm)

Reliability Testing Result

VFHL1111C-4B23C-TR

1. Reliability Testing Result

Test item	Standard	Test condition	Duration	Failure
Operating life	EIAJ ED-4701 /100(101)	Ta=25°C I _F =30mA	1,000h	0 / 20
High temperature operating life	EIAJ ED-4701 /100(101)	Ta=85°C I _F =20mA	1,000h	0 / 20
Low temperature operating life	EIAJ ED-4701 /100(101)	Ta=-40°C I _F =30mA	1,000h	0 / 20
Wet high temperature operating life	EIAJ ED-4701 /100(102)	Ta=60°C 90% I _F =30mA	1,000h	0 / 20
High temperature storage life	EIAJ ED-4701 /200(201)	Ta=105°C	1,000h	0 / 20
Low temperature storage life	EIAJ ED-4701 /200(202)	Ta=-40°C	1,000h	0 / 20
Wet high temperature storage life	EIAJ ED-4701 /200(202)	Ta=60°C 90%	1,000h	0 / 20
Thermal shock	EIAJ ED-4701 /100(105)	Ta=-40°C ~ 105°C (each 15min)	1,000 cycles	0 / 20
Resistance to reflow soldering	EIAJ ED-4701 /300(301)	Moisture soak : 30°C 70% 168h Preheating : 150 to 180°C 120sec MAX. Soldering : 260°C 5sec	2 times	0 / 20
Electrostatic discharge (ESD) ※1	EIAJ ED-4701 /300(304)	C=100pF R2=1.5kΩ ±2,000V	Once of each polarity	0 / 10
Vibration, variable frequency	EIAJ ED-4701 /400(403)	98.1m/s ² (10G) 100 to 2,000Hz 20min. sweep XYZ direction	2h of each direction	0 / 10

※1 Reference test

2. Failure Criteria

Item	Symbol	Conditions	Failure criteria
Luminous intensity	I _V	I _F =20mA	Testing min. value < Standard min. value × 0.5
Forward voltage	V _F	I _F =20mA	Testing max. value ≥ Standard max. value × 1.2
Reverse current	I _R	V _R =5V	Testing max. value ≥ Standard max. value × 2.5
Cosmetic appearance	-	-	Notable discoloration, deformation and cracking

Special notice to customers using the products and technical information shown in this data sheet

- 1) The technical information shown in the data sheets are limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license.
- 2) For the purpose of product improvement, the specifications, characteristics and technical data described in the data sheets are subject to change without prior notice. Therefore it is recommended that the most updated specifications be used in your design.
- 3) When using the products described in the data sheets, please adhere to the maximum ratings for operating voltage, heat dissipation characteristics, and other precautions for use. We are not responsible for any damage which may occur if these specifications are exceeded.
- 4) The products that have been described to this catalog are manufactured so that they will be used for the electrical instrument of the benchmark (OA equipment, telecommunications equipment, AV machine, home appliance and measuring instrument).
The application of aircrafts, space borne application, transportation equipment, medical equipment and nuclear power control equipment, etc. needs a high reliability and safety, and the breakdown and the wrong operation might influence the life or the human body. Please consult us beforehand if you plan to use our product for the usages of aircrafts, space borne application, transportation equipment, medical equipment and nuclear power control equipment, etc. except OA equipment, telecommunications equipment, AV machine, home appliance and measuring instrument.
- 5) In order to export the products or technologies described in this data sheet which are under the "Foreign Exchange and Foreign Trade Control Law," it is necessary to first obtain an export permit from the Japanese government.
- 6) No part of this data sheet may be reprinted or reproduced without prior written permission from Stanley Electric Co., Ltd.
- 7) The most updated edition of this data sheet can be obtained from the address below:
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